

## EAST Search History

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	1	("20070071904").PN.	US-PGPUB	OR	OFF	2008/05/05 08:37
L2	1992	((427/99.1) or (427/99.5) or (427/305) or (427/437) or (427/443.1)).OCLS.	US-PGPUB; USPAT	OR	OFF	2008/05/05 08:47
L3	1487	2 and (electroless or electrolessly)	US-PGPUB; USPAT	OR	ON	2008/05/05 08:48
L4	6	3 and ((reducing or reductant or reducer) same (glyoxylic) same (hypophosphorous))	US-PGPUB; USPAT	OR	ON	2008/05/05 08:48
L5	19	(electroless or electrolessly) and ((reducing or reductant or reducer) same (glyoxylic) same (hypophosphorous))	US-PGPUB; USPAT	OR	ON	2008/05/05 08:50
L6	13	5 not 4	US-PGPUB; USPAT	OR	ON	2008/05/05 08:50
L7	75	(electroless or electrolessly) and ((reducing or reductant or reducer) same (glyoxylic) same (hypophosphite))	US-PGPUB; USPAT	OR	ON	2008/05/05 08:56
L8	57	7 not 5	US-PGPUB; USPAT	OR	ON	2008/05/05 08:56
L9	14	((reducing or reductant or reducer) same (glyoxylic) same (hypophosphite))	FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/05/05 09:02
L10	18	((glyoxylic) same (hypophosphite or hypophosphorous))	FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/05/05 09:03
L11	4	10 not 9	FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/05/05 09:03
L12	38	((glyoxylic) same (hypophosphite or hypophosphorous))	USPAT	OR	ON	2008/05/05 09:08
L13	12	12 not 7	USPAT	OR	ON	2008/05/05 09:08
L14	117	((glyoxylic) and (hypophosphite or hypophosphorous))	USPAT	OR	ON	2008/05/05 09:09
L15	41	14 and (electroless or electrolessly)	USPAT	OR	ON	2008/05/05 09:09

L16	15	15 not 7	USPAT	OR	ON	2008/05/05 09:09
L17	138	((glyoxylic) and (hypophosphite or hypophosphorous))	US-PGPUB	OR	ON	2008/05/05 09:12
L18	69	17 and (electroless or electrolessly)	US-PGPUB	OR	ON	2008/05/05 09:13
L19	20	18 not 7	US-PGPUB	OR	ON	2008/05/05 09:13
L20	2	((oxoacetic or formylformic or oxoethanoic) same (hypophosphite or hypophosphorous))	USPAT	OR	ON	2008/05/05 09:15
L21	0	((oxoacetic or formylformic or oxoethanoic or glyoxylic) near20 (hypophosphite or hypophosphorous))	USOCR	OR	ON	2008/05/05 09:16
L22	2	((oxoacetic or formylformic or oxoethanoic or glyoxylic) and (hypophosphite or hypophosphorous))	USOCR	OR	ON	2008/05/05 09:16
L23	0	((oxoacetic or formylformic or oxoethanoic) and (hypophosphite or hypophosphorous))	FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/05/05 09:17
L24	22	((oxoacetic or formylformic or oxoethanoic or glyoxylic) same (formalin))	USPAT	OR	ON	2008/05/05 09:30
L25	123	((formalin) same (hypophosphite or hypophosphorous))	USPAT	OR	ON	2008/05/05 09:31
L26	40	((formalin) same (hypophosphite or hypophosphorous))	FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/05/05 09:45
L27	3	((formalin) near20 (hypophosphite or hypophosphorous))	USOCR	OR	ON	2008/05/05 09:48
L28	59	((formalin) same (hypophosphite or hypophosphorous))	US-PGPUB	OR	ON	2008/05/05 09:48
L29	1037	2 and ((electroless or electrolessly) with (cu or copper))	US-PGPUB; USPAT	OR	ON	2008/05/05 09:54
L30	4	29 and (silicon with (substrate or surface) with roughness)	US-PGPUB; USPAT	OR	ON	2008/05/05 09:55
L31	3700	(silicon with (substrate or surface) with roughness)	US-PGPUB; USPAT	OR	ON	2008/05/05 09:56

L32	863	31 with wafer	US-PGPUB; USPAT	OR	ON	2008/05/05 09:56
L33	1	32 with (electroless or electrolessly)	US-PGPUB; USPAT	OR	ON	2008/05/05 09:56
L34	37	32 and (electroless or electrolessly)	US-PGPUB; USPAT	OR	ON	2008/05/05 09:56
L35	158	31 with wafer with nm	US-PGPUB; USPAT	OR	ON	2008/05/05 09:58
L36	6	35 and (electroless or electrolessly)	US-PGPUB; USPAT	OR	ON	2008/05/05 09:58
L37	5391	silicon with wafer with nm	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/05/05 10:00
L38	197	37 with roughness	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/05/05 10:00
L39	21	38 and (electroless or electrolessly or plated or plating)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/05/05 10:00
L40	104	(silicon with wafer) with (electroless or electrolessly)	US-PGPUB; USPAT	OR	ON	2008/05/05 10:05
L41	1867	(silicon with wafer) and ((electroless or electrolessly) with (cu or copper))	US-PGPUB; USPAT	OR	ON	2008/05/05 10:06
L42	178	41 and ((thick or thickness) with (cu or copper) with nm)	US-PGPUB; USPAT	OR	ON	2008/05/05 10:06
L43	32	41 and ((thick or thickness) with (cu or copper) with nm with (plated or plating))	US-PGPUB; USPAT	OR	ON	2008/05/05 10:06
L44	1	wo-0149898-\$.did.	FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/05/05 10:15
L45	2	((("7045461") or ("7179741")). PN.	USPAT	OR	OFF	2008/05/05 10:32
L46	254	(427/99.1).OCLS.	US-PGPUB; USPAT	OR	OFF	2008/05/05 10:33

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